

DesignCon 2016 Honors Dr. Eric Bogatin with Prestigious Engineer of the Year Award

Dr. Bogatin was Selected by the DesignCon Community Based on his Many Contributions to the Engineering Industry

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SANTA CLARA, Calif., Jan. 21, 2016 /PRNewswire/ -- DesignCon, produced by UBM Americas, today announced Dr. Eric Bogatin of the Teledyne LeCroy Signal Integrity Academy as the recipient of the 2016 Engineer of the Year Award. Recognized for his leadership, creativity, and out-of-the-box thinking, Dr. Bogatin was awarded earlier today during DesignCon, being held this week, January 19-21, at the Santa Clara Convention Center. For additional information please visit: designcon.com.

"I am thrilled and honored to be selected as engineer of the year," said Dr. Bogatin. "Just having been nominated and making the finalist list was a thrill. I felt honored to be in the company of some of the industry experts like Istvan Novak, Bob Shaefer and the late Steve Weir."

The DesignCon Engineer of the Year Award honors professionals within the Engineering space for innovation, forward thinking and positive contributions to the design/test of chips, boards, or systems. After peers nominated Dr. Bogatin, he was carefully chosen by the editors of EDN/EETimes as a finalist and again voted the winner by the DesignCon community—likely based on his long history as a supporter and industry educator of the event.

As an industry-wide resource for all things SI and PI, Dr. Bogatin's books, public classes, and online resources have continued to enrich and educate the engineering community for decades. He has continued to assist in helping engineering professionals through his participation with DesignCon each year. This year he led an all-day Signal Integrity Bootcamp, participated in a speed-training in the Chiphead Theater and contributed to multiple panels.

"Eric is so deserving of the DesignCon Engineer of the Year Award," said DesignCon Technical Program Director, Janine Love. "He has been involved in DesignCon since its very beginnings, and he remains committed to the spirit of DesignCon by continuing to teach and share what he knows with others. I will always be grateful to Eric for his service to DesignCon, and congratulate him heartily on being selected by his peers as the DesignCon Engineer of the Year."

For more information on **DesignCon 2016 Engineer of the Year Award**, please visit:
designcon.com/santaclara/awards/

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About DesignCon

DesignCon is the world's premier conference for chip, board and systems design engineers in the high-speed communications and semiconductor communities. DesignCon, created by engineers for engineers, takes place annually in Silicon Valley and remains the largest gathering of chip, board and systems designers in the country. This three-day technical conference and expo combines technical paper sessions, tutorials, industry panels, product demos and exhibits from the industry's leading experts and solutions providers. More information is available at: designcon.com/santaclara. DesignCon is organized by UBM Americas, a part of UBM plc (UBM.L), an Events First marketing and communications services business. For more information, visit ubmamericas.com.

Contact:

Kimberly Samra

DesignCon PR

DesignConPR@ubm.com

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